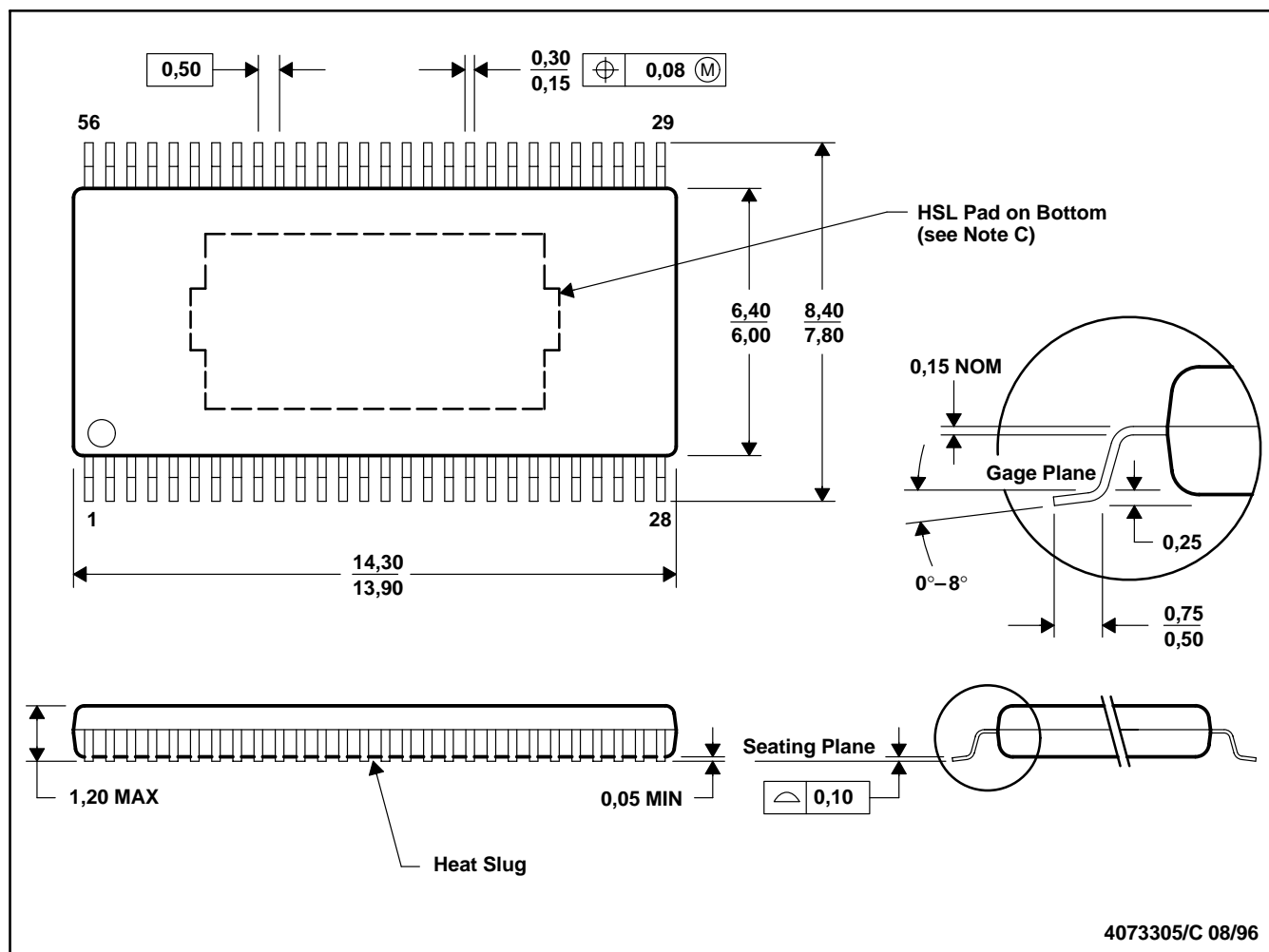


DCA (R-PDSO-G56)

PowerPad™ PLASTIC SMALL-OUTLINE PACKAGE



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Thermally enhanced molded plastic package with a exposed heat slug (HSL) on bottom.

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